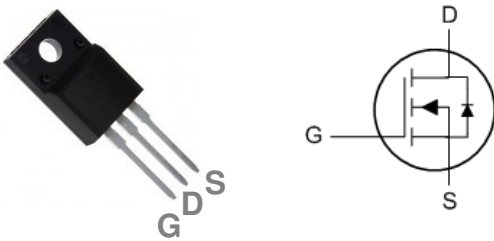


General Description

These N-Channel enhancement mode power field effect transistors are using advanced super junction technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply

TO220F Pin Configuration



Features

- 20A,650V, $R_{DS(ON)} = 0.19\Omega @ V_{GS} = 10V$
- Low gate charge (typical 52nC)
- Low C_{rss} (typical 8.5 pF)
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- High efficient switched mode power supplies
- TV Power
- Adapter/charger
- Server Power
- PV Inverter / UPS

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	± 30	V
I_D	Drain Current – Continuous ($T_C=25^\circ\text{C}$)	20	A
	Drain Current – Continuous ($T_C=100^\circ\text{C}$)	12.5	A
I_{DM}	Drain Current – Pulsed (Note 1)	80	A
EAS	Single Pulse Avalanche Energy (Note 2)	248	mJ
IAS	Single Pulse Avalanche Current (Note 2)	6	A
P_D	Power Dissipation ($T_C=25^\circ\text{C}$)	70	W
	Power Dissipation – Derate above 25°C	0.56	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.8	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	650	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1mA$	---	0.6	---	$V/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=600V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	10	μA
		$V_{DS}=600V, V_{GS}=0V, T_J=125^\circ\text{C}$			100	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	± 100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=10A$	---	190	210	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	3.5	5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-6.3	---	$mV/^\circ\text{C}$

Dynamic and switching Characteristics

Q_g	Total Gate Charge (10V)	$V_{DS}=480V, V_{GS}=10V, I_D=20A$ (Note 3,4)	---	52	---	nC
Q_{gs}	Gate-Source Charge		---	11	---	
Q_{gd}	Gate-Drain Charge		---	22	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=380V, V_{GS}=10V, R_G=3.5\Omega,$ $I_D=18A$ (Note 3,4)	---	16	---	ns
T_r	Rise Time		---	45	---	
$T_{d(off)}$	Turn-Off Delay Time		---	30	---	
T_f	Fall Time		---	40	---	
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, F=1MHz$	---	1515	---	pF
C_{oss}	Output Capacitance		---	58	---	
C_{rss}	Reverse Transfer Capacitance		---	8.5	---	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	20	A
I_{SM}	Pulsed Source Current		---	---	80	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=20A, T_J=25^\circ\text{C}$	---	0.9	1.3	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0V, I_S=20A, di/dt=100A/\mu s$,	---	370	---	nS
Q_{rr}	Reverse Recovery Charge	$T_J=25^\circ\text{C}$ (Note 3)	---	5	---	μC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=50V, V_{GS}=10V, L=13.8mH, I_{AS}=6A, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

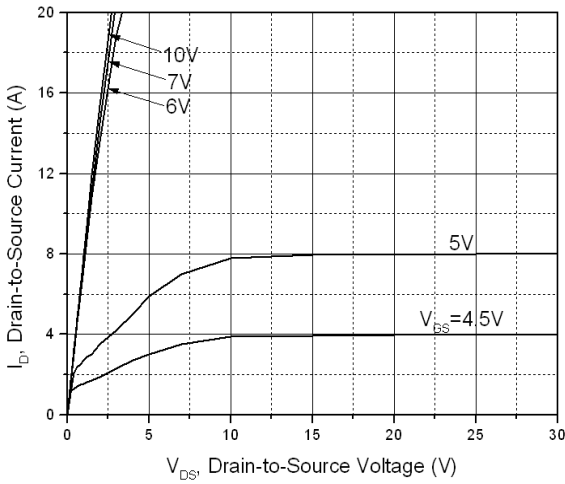


Fig.1 Typical Output Characteristics

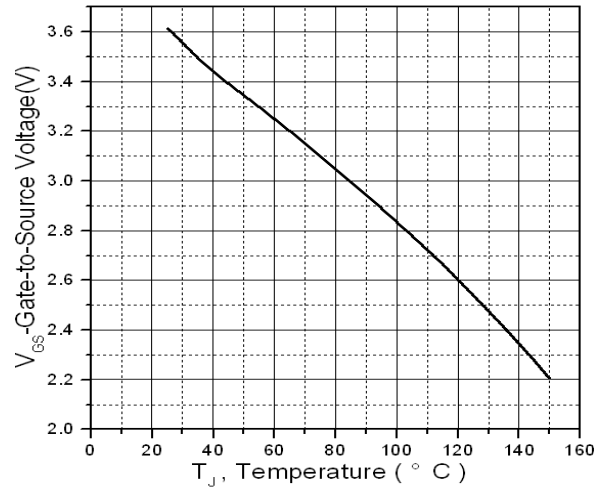


Fig.2 $V_{GS(th)}$ vs. Junction Temperature

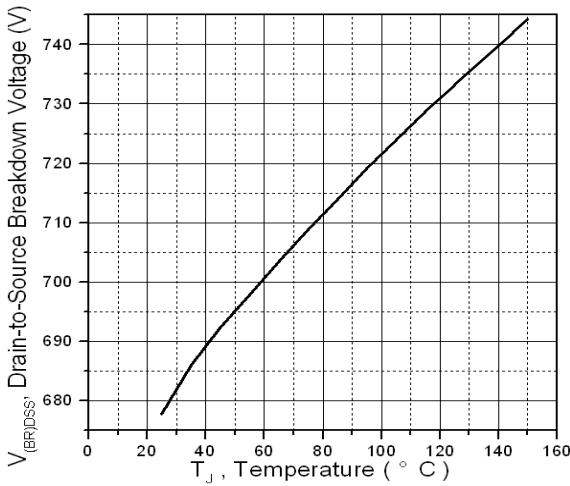


Fig.3 BVDSS vs. Junction Temperature

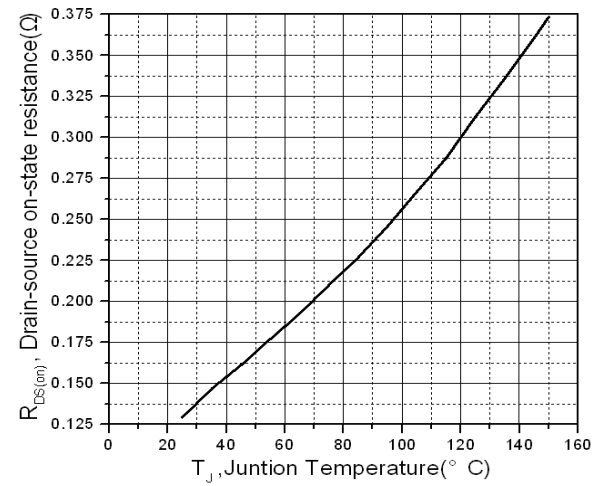


Fig.4 $R_{DS(on)}$ vs. Junction Temperature

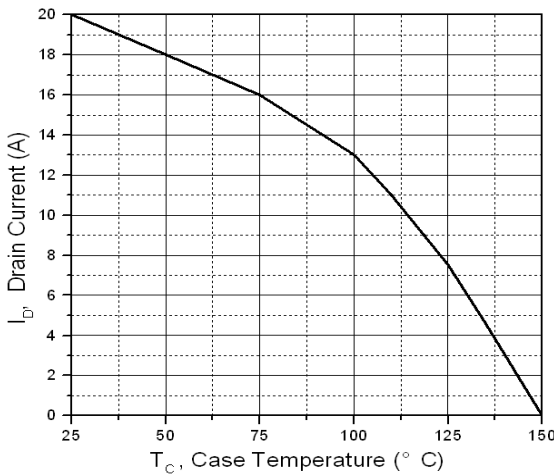


Fig.5 I_D vs. Case Temperature

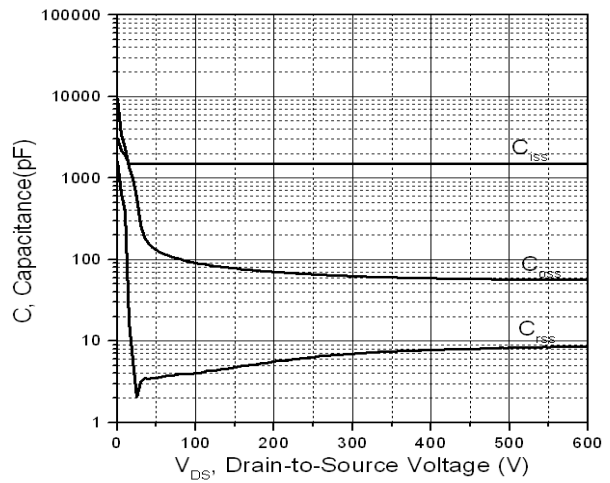


Fig.6 Typical Capacitance vs. V_{DS}

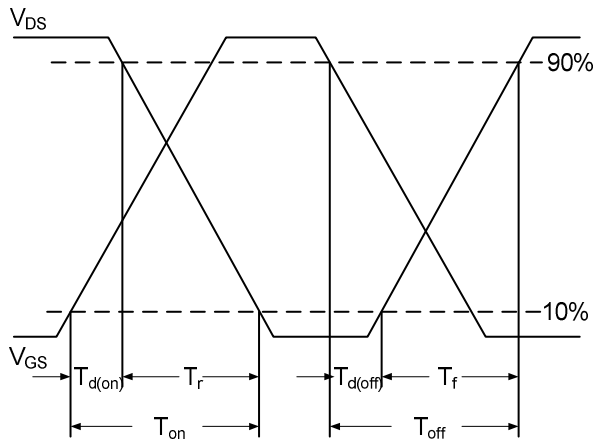
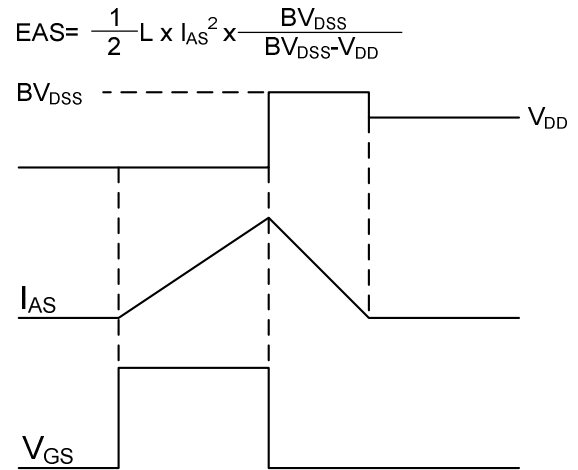


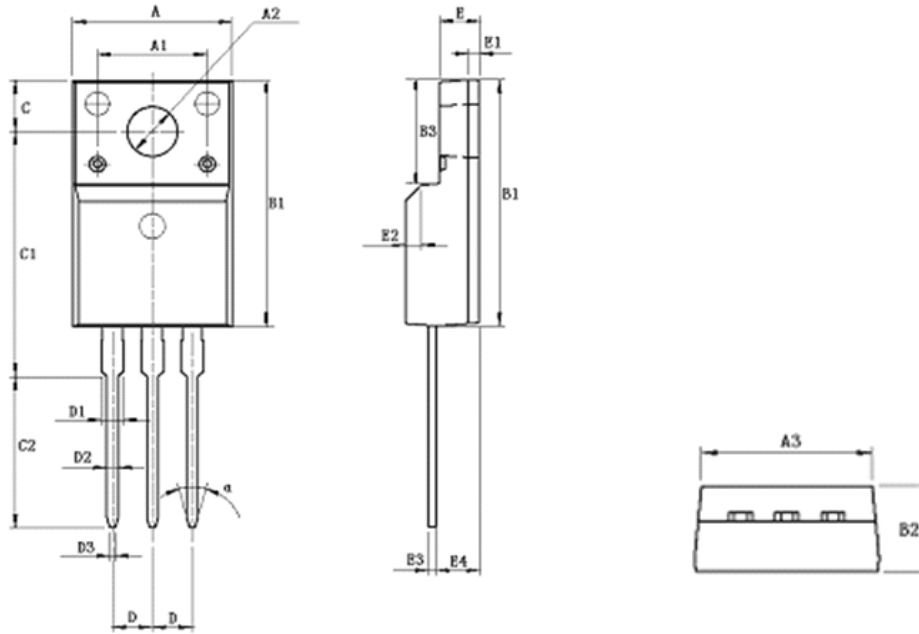
Fig.7 Switching Time Waveform



$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

Fig.8 EAS Waveform

TO220F PACKAGE OUTLINE DIMENSION



Symbol	Dimension In Millimeters			Dimension In Inches		
	Min	Nom	Max	Min	Nom	Max
A	9.960	10.160	10.360	0.392	0.400	0.408
A1		7.000		0.276	0.000	0.000
A2	3.080	3.180	3.280	0.121	0.125	0.129
A3	9.260	9.460	9.660	0.365	0.372	0.380
B1	15.670	15.870	16.070	0.617	0.625	0.633
B2	4.500	4.700	4.900	0.177	0.185	0.193
B3	6.480	6.680	6.880	0.255	0.263	0.271
C	3.200	3.300	3.400	0.126	0.130	0.134
C1	15.600	15.800	16.000	0.614	0.622	0.630
C2	9.550	9.750	9.950	0.376	0.384	0.392
D	2.54 (TYP)			1.00 (TYP)		
D1	-	-	1.470	-	-	0.058
D2	0.700	0.800	0.900	0.028	0.031	0.035
D3	0.250	0.350	0.450	0.010	0.014	0.018
E	2.340	2.540	2.740	0.092	0.100	0.108
E1	0.700			0.028		
E2	1.0*45 ⁰			1.0*45 ⁰		
E3	0.450	0.500	0.600	0.018	0.020	0.024
E4	2.560	2.760	2.960	0.101	0.109	0.117
θ	30 ⁰			30 ⁰		